



January 2010

# FDS6692A

## N-Channel PowerTrench® MOSFET

30V, 9A, 11.5mΩ

## Features

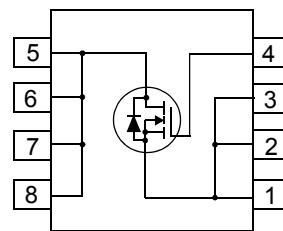
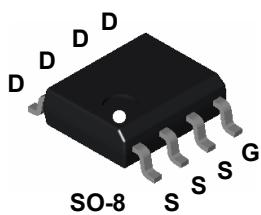
- $R_{DS(ON)} = 11.5\text{m}\Omega$ ,  $V_{GS} = 10\text{V}$ ,  $I_D = 9\text{A}$
- $R_{DS(ON)} = 14.5\text{m}\Omega$ ,  $V_{GS} = 4.5\text{V}$ ,  $I_D = 8.2\text{A}$
- High performance trench technology for extremely low  $R_{DS(ON)}$
- Low gate charge

## Applications

#### ■ DC/DC converters

## **General Description**

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low  $R_{DS(ON)}$  and fast switching speed.



**MOSFET Maximum Ratings**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain to Source Voltage	30	V
$V_{GS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Drain Current	9	A
	Continuous ( $T_A = 25^\circ\text{C}$ , $V_{GS} = 10\text{V}$ , $R_{0JA} = 85^\circ\text{C/W}$ )		
	Continuous ( $T_A = 25^\circ\text{C}$ , $V_{GS} = 4.5\text{V}$ , $R_{0JA} = 85^\circ\text{C/W}$ )		
$E_{AS}$	Pulsed	48	A
	Single Pulse Avalanche Energy (Note 1)	79	mJ
$P_D$	Power dissipation	1.47	W
$T_J$ , $T_{STG}$	Operating and Storage Temperature	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

$R_{0JA}$	Thermal Resistance, Junction to Ambient at 10 seconds (Note 3)	50	$^\circ\text{C/W}$
$R_{0JA}$	Thermal Resistance, Junction to Ambient at 1000 seconds (Note 3)	85	$^\circ\text{C/W}$

**Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS6692A	FDS6692A	SO-8	330mm	12mm	2500 units

**Electrical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**Off Characteristics**

$B_{VDSS}$	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$	30	-	-	V
$\Delta B_{VDSS}$ $\Delta T_J$	Breakdown Voltage Temp. Coefficient	$I_D = 250\mu\text{A}$ , Referenced to $25^\circ\text{C}$	-	21	-	$\text{mV}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{V}$	-	-	1	$\mu\text{A}$
		$V_{GS} = 0\text{V}$ $T_J = 150^\circ\text{C}$	-	-	250	
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA

**On Characteristics**

$V_{GS(TH)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250\mu\text{A}$	1.2	-	2.5	V
$\Delta V_{GS(TH)}$ $\Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$ , Referenced to $25^\circ\text{C}$	-	-5	-	$\text{mV}/^\circ\text{C}$
$R_{DS(ON)}$	Drain to Source On Resistance	$I_D = 9\text{A}$ , $V_{GS} = 10\text{V}$	-	8.2	11.5	$\text{m}\Omega$
		$I_D = 8.2\text{A}$ , $V_{GS} = 4.5\text{V}$	-	11	14.5	
		$I_D = 9\text{A}$ , $V_{GS} = 10\text{V}$ , $T_J = 150^\circ\text{C}$	-	13	19	

**Dynamic Characteristics**

$C_{ISS}$	Input Capacitance	$V_{DS} = 15\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$	-	1210	1610	pF	
$C_{OSS}$	Output Capacitance		-	330	440	pF	
$C_{RSS}$	Reverse Transfer Capacitance		-	138	210	pF	
$R_G$	Gate Resistance	$f = 1\text{MHz}$	-	2.0	-	$\Omega$	
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS} = 0\text{V}$ to 10V	-	22	29	nC	
$Q_{g(5)}$	Total Gate Charge at 5V	$V_{GS} = 0\text{V}$ to 5V	$V_{DD} = 15\text{V}$ $I_D = 9\text{A}$ $I_g = 1.0\text{mA}$	-	12	16	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0\text{V}$ to 1V		-	0.93	1.2	nC
$Q_{gs}$	Gate to Source Gate Charge			-	3	-	nC
$Q_{gs2}$	Gate Charge Threshold to Plateau			-	2.1	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		-	4.8	-	nC	

**Switching Characteristics ( $V_{GS} = 10V$ )**

$t_{ON}$	Turn-On Time	$V_{DD} = 15V, I_D = 9A$ $V_{GS} = 10V, R_{GS} = 6.2\Omega$	-	-	60	ns
$t_{d(ON)}$	Turn-On Delay Time		-	8	-	ns
$t_r$	Rise Time		-	32	-	ns
$t_{d(OFF)}$	Turn-Off Delay Time		-	33	-	ns
$t_f$	Fall Time		-	13	-	ns
$t_{OFF}$	Turn-Off Time		-	-	69	ns

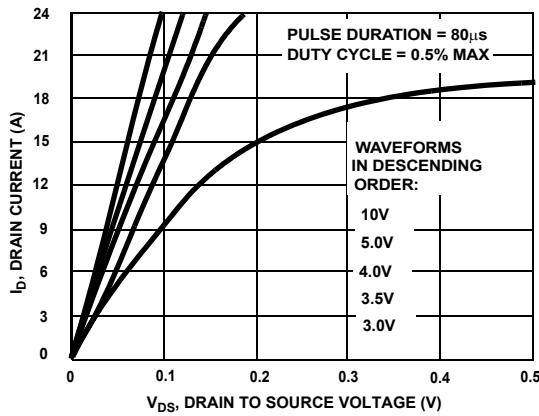
**Drain-Source Diode Characteristics**

$V_{SD}$	Source to Drain Diode Voltage	$I_{SD} = 9A$	-	-	1.25	V
		$I_{SD} = 2.1A$	-	-	1.0	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 9A, dI_{SD}/dt=100A/\mu s$	-	-	27	ns
$Q_{RR}$	Reverse Recovered Charge	$I_{SD} = 9A, dI_{SD}/dt=100A/\mu s$	-	-	17	nC

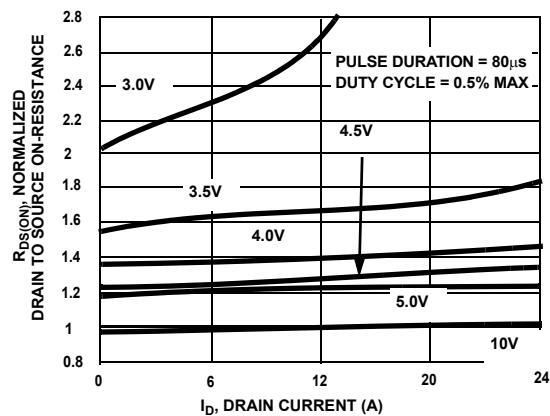
**Notes:**

- 1: Starting  $T_J = 25^\circ C$ ,  $L = 0.3mH$ ,  $I_{AS} = 23A$ ,  $V_{DD} = 27V$ ,  $V_{GS} = 10V$ .
- 2:  $R_{0JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{0JC}$  is guaranteed by design while  $R_{0JA}$  is determined by the user's board design.
- 3:  $R_{0JA}$  is measured with 1.0 in<sup>2</sup> copper on FR-4 board

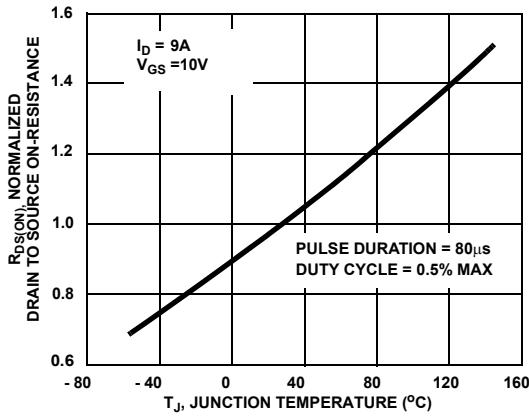
**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted



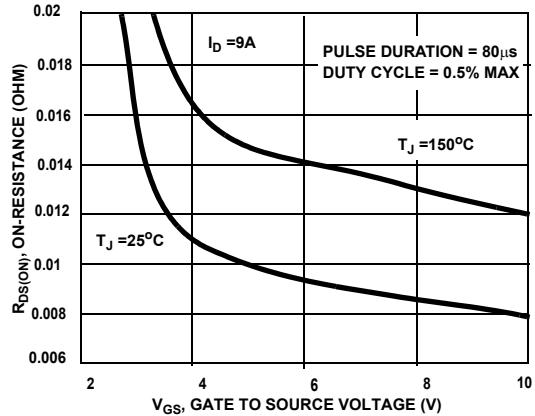
**Figure 1. On Region Characteristics**



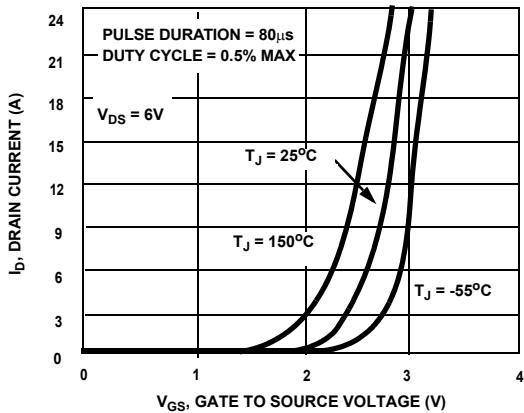
**Figure 2. On-Resistance Variation with Drain Current and Gate Voltage**



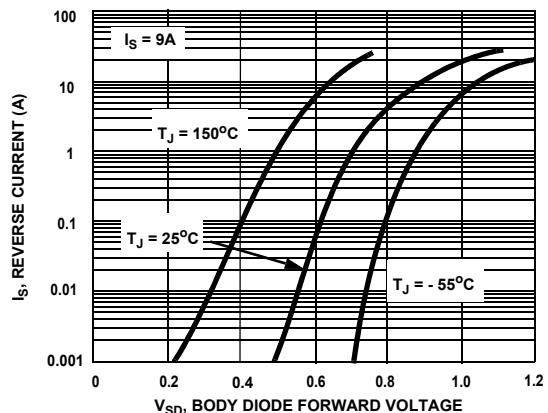
**Figure 3. On Resistance Variation with Temperature**



**Figure 4. On-Resistance Variation with Gate-to-Source Voltage**



**Figure 5. Transfer Characteristics**



**Figure 6. Body Diode Forward Voltage Variation With Source Current and Temperature**

**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted

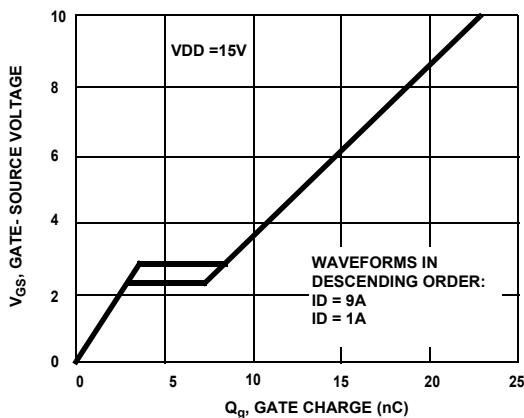


Figure 7. Gate Charge Characteristics

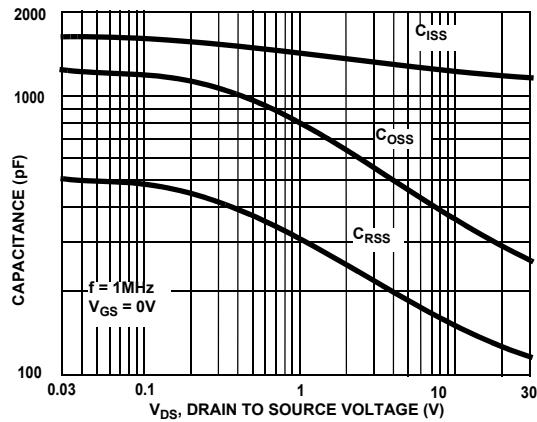


Figure 8. Capacitance Characteristics

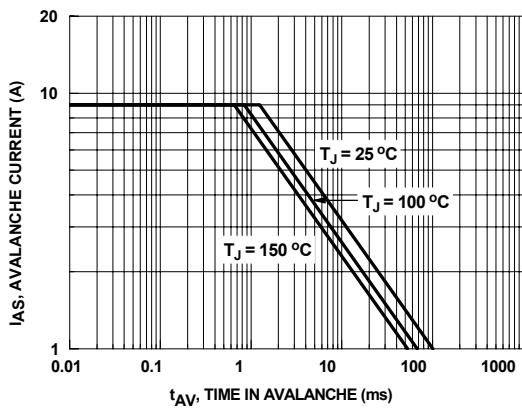


Figure 9. Unclamped Inductive Switching Capability

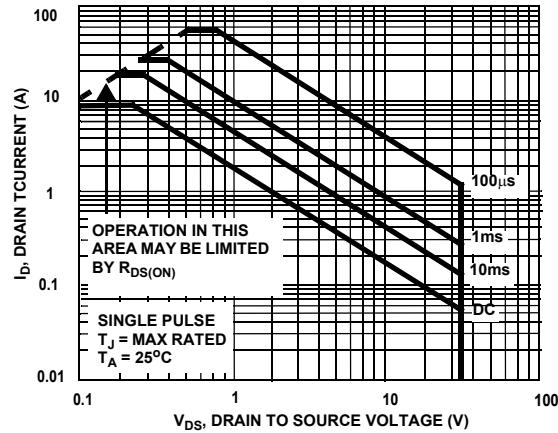


Figure 10. Safe Operating Area

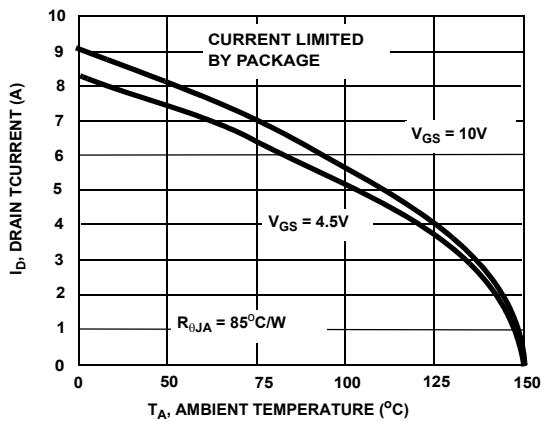


Figure 11. Maximum Continuous Drain Current vs Ambient Temperature

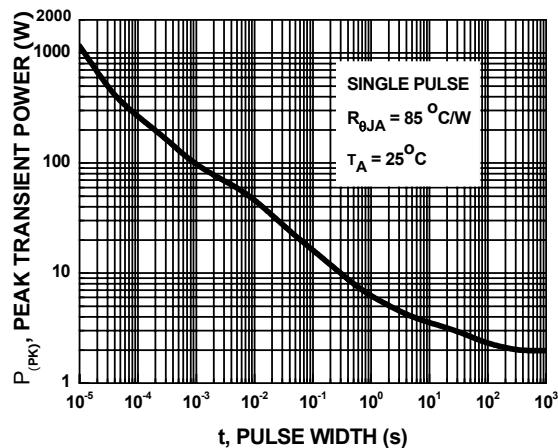


Figure 12. Single Maximum Power Dissipation

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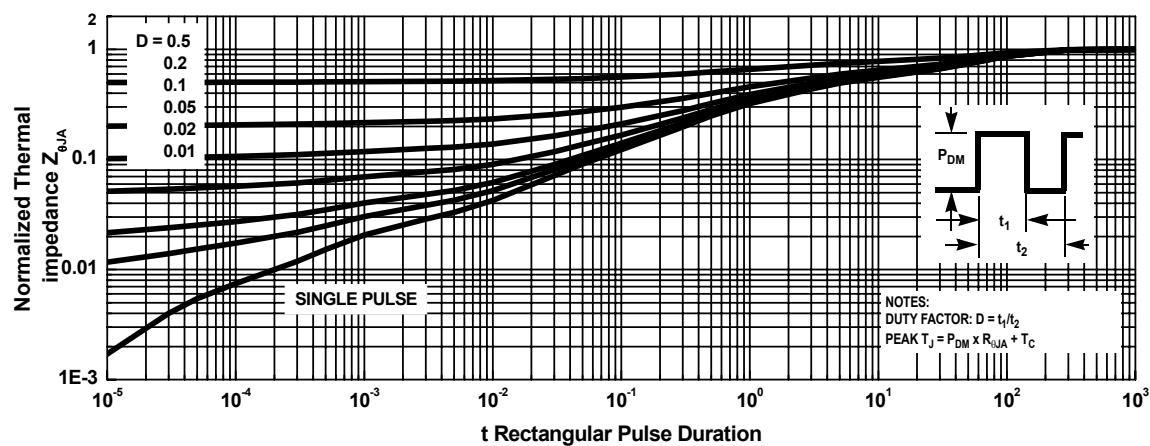


Figure 13. Transient Thermal Response Curve



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